

IN THE CLAIMS:

Please amend the claims as follows.

Claim 1 (Currently Amended): A solid-state imaging apparatus comprising:

a package having,

a hollow portion that extends in a predetermined direction of the package, and

a mounting portion that protrudes into the hollow portion and includes a first planar portion and a second planar portion formed stepped with respect to the first planar portion;

a solid-state imaging element disposed on the first planar portion of the mounting portion and[[,]] having an energy ray sensitive portion; and

a signal processing circuit disposed on the second planar portion and that processes[[,]]

~~processing~~ signals output from said solid-state imaging element and including a load resistor electrically connected to an output terminal of the solid-state imaging element; [[and]]

~~a package, housing the solid-state imaging element and the signal processing circuit,~~

wherein the load resistor and the output terminal of the solid-state imaging element are electrically and directly connected via a bonding wire,

wherein the signal processing circuit ~~is positioned at a planar portion of the package that differ from a planar portion at which the solid-state imaging element is positioned,~~ and is positioned alongside the solid-state imaging element when viewed from a direction perpendicular to the planar portion at which the solid-state imaging element is positioned.

Claim 2 (Currently Amended): A solid-state imaging apparatus comprising:

a package having,

a hollow portion that extends in a predetermined direction of the package,

and

a mounting portion that protrudes into the hollow portion and includes a

first planar portion and a second planar portion formed stepped with respect to the

first planar portion;

a solid-state imaging element disposed on the first planar portion and[[,]] having an energy ray sensitive portion; and

a signal processing circuit disposed on the second planar portion and that, ~~processing~~ processes signals output from the solid-state imaging element and including a load resistor electrically connected to an output terminal of the solid-state imaging element; [[and]]

~~a package, housing the solid-state imaging element and the signal processing circuit,~~

wherein the package has a first planar portion and a second planar portion, formed to be stepped with respect to the first planar portion, the second planar portion is positioned alongside the first planar portion when viewed from a direction perpendicular to the first and second planar portion,

wherein the load resistor and the output terminal of the solid-state imaging element are electrically and directly connected via a bonding wire, ~~and~~

~~wherein the solid-state imaging element is positioned at the first planar portion, and the load resistor is positioned at the second planar portion.~~

Claim 3 (Canceled).

Claim 4 (Currently Amended): The solid-state imaging apparatus according to Claim 1 or 2,

wherein one end of the load resistor is electrically connected to ~~[[an]]~~ the output terminal of the solid-state imaging element and the other end of the load resistor is grounded; and

wherein the signal processing circuit further includes a buffer amplifier, having a bipolar transistor that is electrically connected to the output terminal of the solid-state imaging element.

Claim 5 (Previously Presented): The solid-state imaging apparatus according to Claim 1 or 2, wherein the signal processing circuit further includes a field-effect transistor making up a source follower circuit with the load resistor.